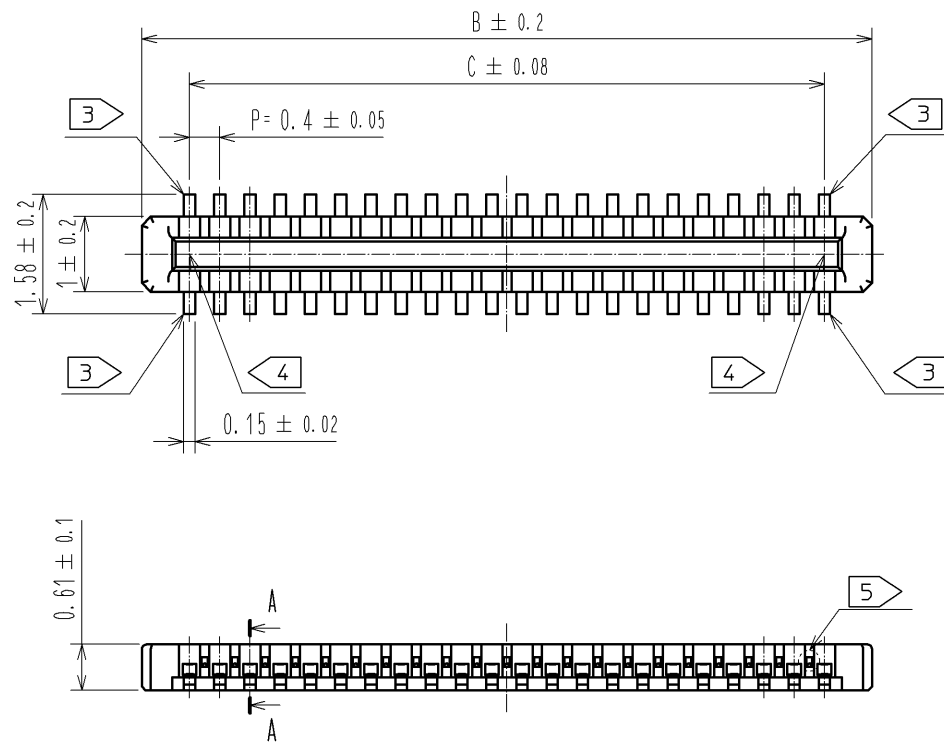
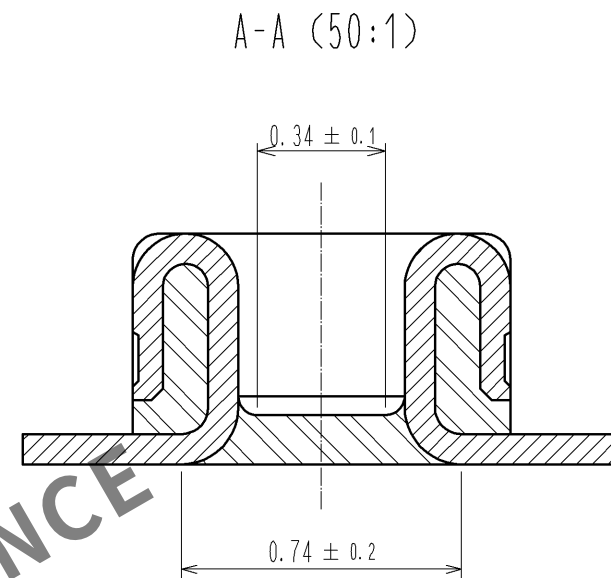


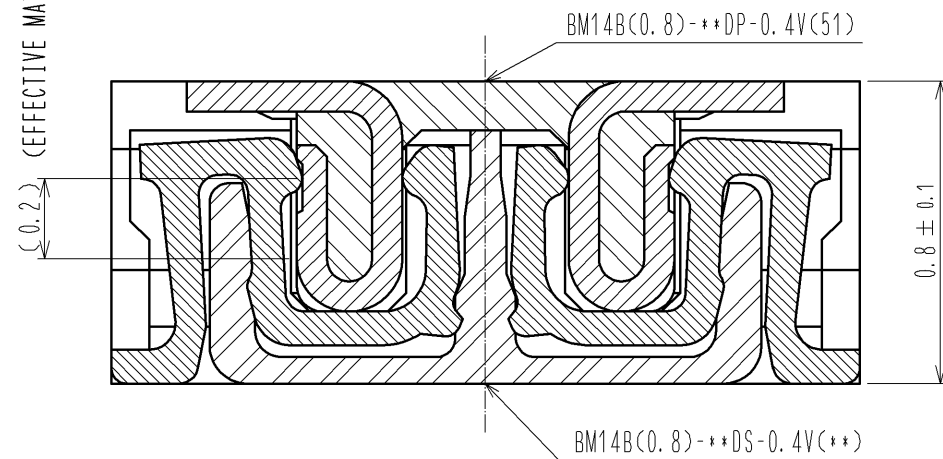


- NOTE) 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
2. CONTACT PLATING SPECIFICATIONS
CONTACT AREA : GOLD 0.05 μ m MIN
SMT LEAD : GOLD 0.05 μ m MIN
UNDERPLATING : NICKEL 1 μ m MIN
(SURFACE : SEALING)
3. EACH CONTACTS AT 4 CORNERS ARE PROVIDED FOR METAL FITTINGS AND GROUNDING PURPOSE.
THEY CAN BE USED ALSO AS A SIGNAL CONTACT.
4. HRS MARK AND CAV No. ARE INDICATED IN APPROX POSITION SHOWN.
5. A PART OF THE WALL COULD BE NOTCHED.

PART No.	CODE No.	B	C
BM14B(0.8)-10DP-0.4V(51)	CL684-8010-0-51	3.66	2.4
BM14B(0.8)-12DP-0.4V(51)	CL684-8042-7-51	4.06	2.8
BM14B(0.8)-20DP-0.4V(51)	CL684-8011-3-51	5.66	4.4
BM14B(0.8)-22DP-0.4V(51)	CL684-8047-0-51	6.06	4.8
BM14B(0.8)-24DP-0.4V(51)	CL684-8012-6-51	6.46	5.2
BM14B(0.8)-30DP-0.4V(51)	CL684-8013-9-51	7.66	6.4
BM14B(0.8)-34DP-0.4V(51)	CL684-8014-1-51	8.46	7.2
BM14B(0.8)-40DP-0.4V(51)	CL684-8015-4-51	9.66	8.4
BM14B(0.8)-50DP-0.4V(51)	CL684-8016-7-51	11.66	10.4
BM14B(0.8)-60DP-0.4V(51)	CL684-8002-2-51	13.66	12.4

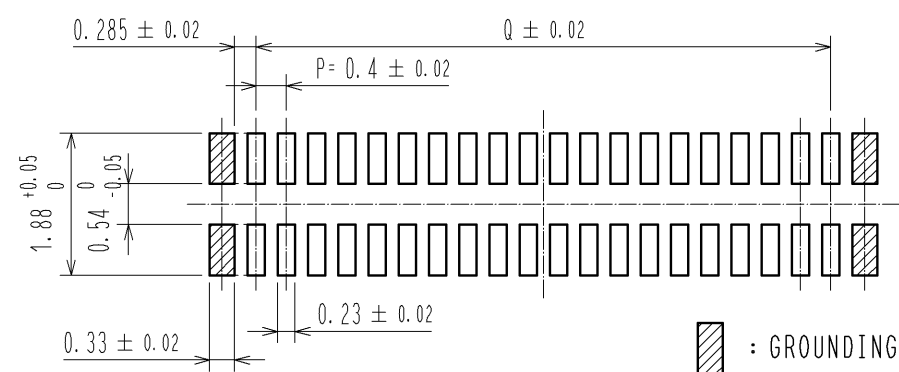


ENGAGEMENT FIGURE (50:1)



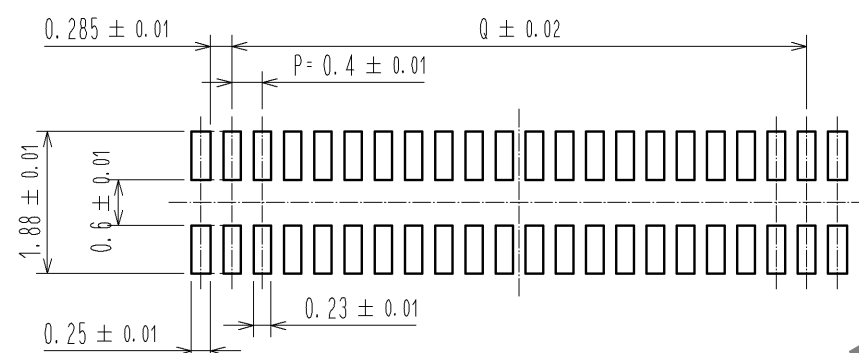
3	PS	CLEAR (ENBOSSED CARRIER TAPE)	6	PS	CLEAR (REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	2	5	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	4	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS
UNITS mm		SCALE 10:1	COUNT 1	DESCRIPTION OF REVISIONS DIS-H-008082	DESIGNED SH. HOSODA
HIROSE ELECTRIC CO., LTD.		APPROVED : KH. IKEDA	09.11.24	DRAWING NO. EDC3-322328-04	DATE 13.08.03
		CHECKED : WR. FUKUCHI	09.11.24	PART NO. BM14B(0.8)-*DP-0.4V(51)	
		DESIGNED : YH. HASEGAWA	09.11.20	CODE NO. CL684	
		DRAWN : YH. HASEGAWA	09.11.20		

◆ RECOMMENDED PCB LAYOUT

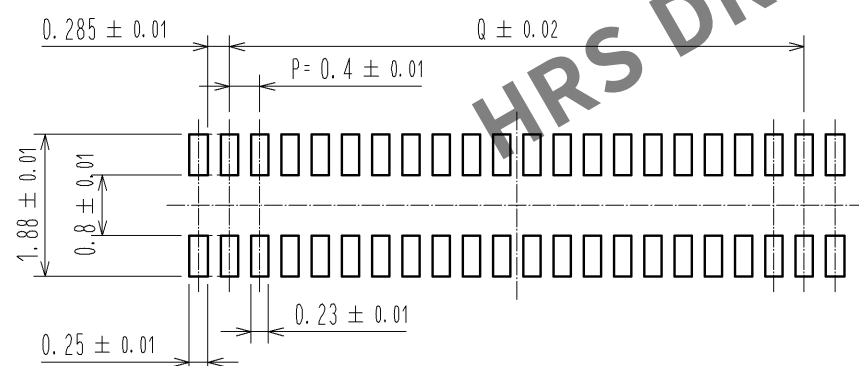


◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 μm

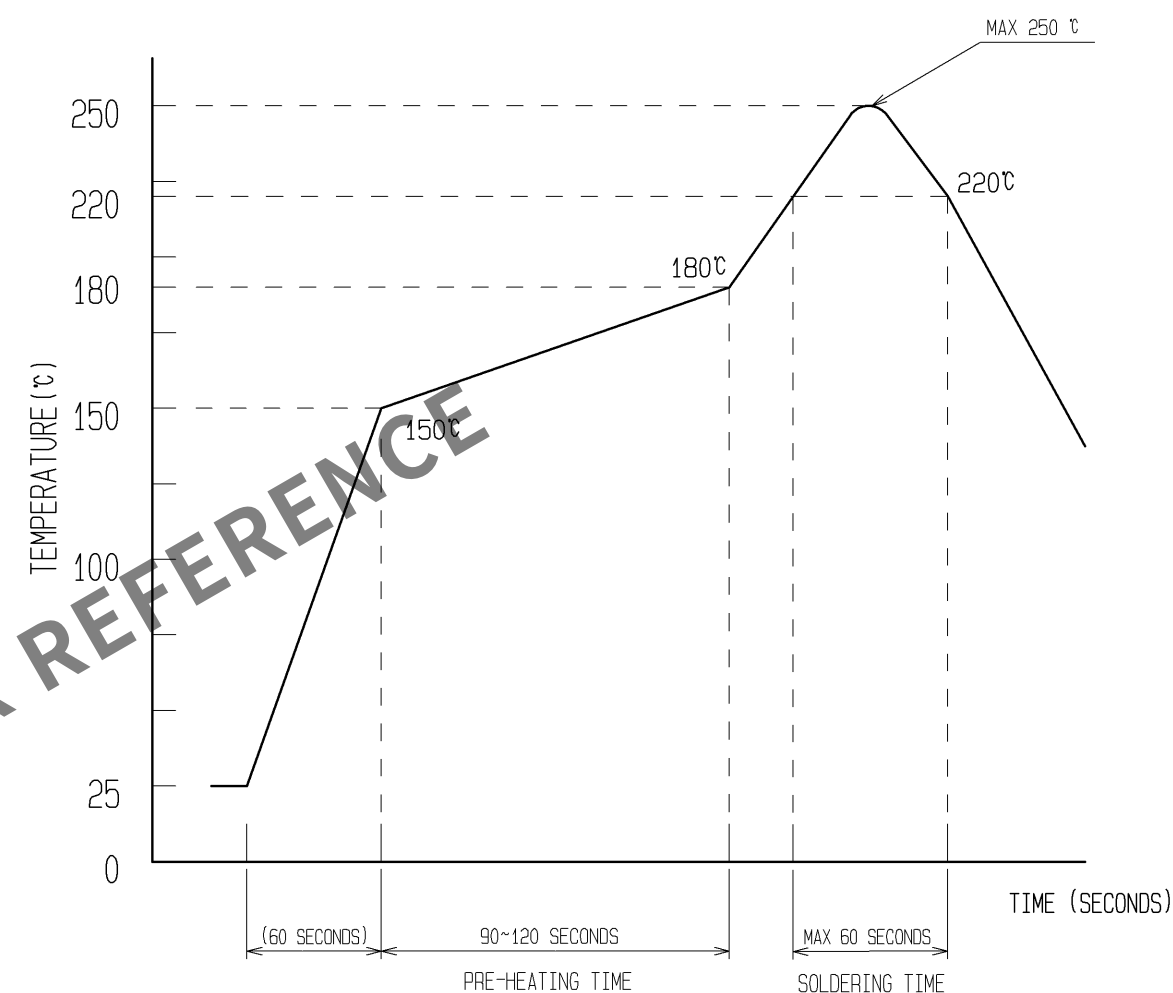


METAL MASK THICKNESS : 120 μm



PART No.	Q
BM14B(0.8)-10DP-0.4V(51)	1.6
BM14B(0.8)-12DP-0.4V(51)	2.0
BM14B(0.8)-20DP-0.4V(51)	3.6
BM14B(0.8)-22DP-0.4V(51)	4.0
BM14B(0.8)-24DP-0.4V(51)	4.4
BM14B(0.8)-30DP-0.4V(51)	5.6
BM14B(0.8)-34DP-0.4V(51)	6.4
BM14B(0.8)-40DP-0.4V(51)	7.6
BM14B(0.8)-50DP-0.4V(51)	9.6
BM14B(0.8)-60DP-0.4V(51)	11.6

6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



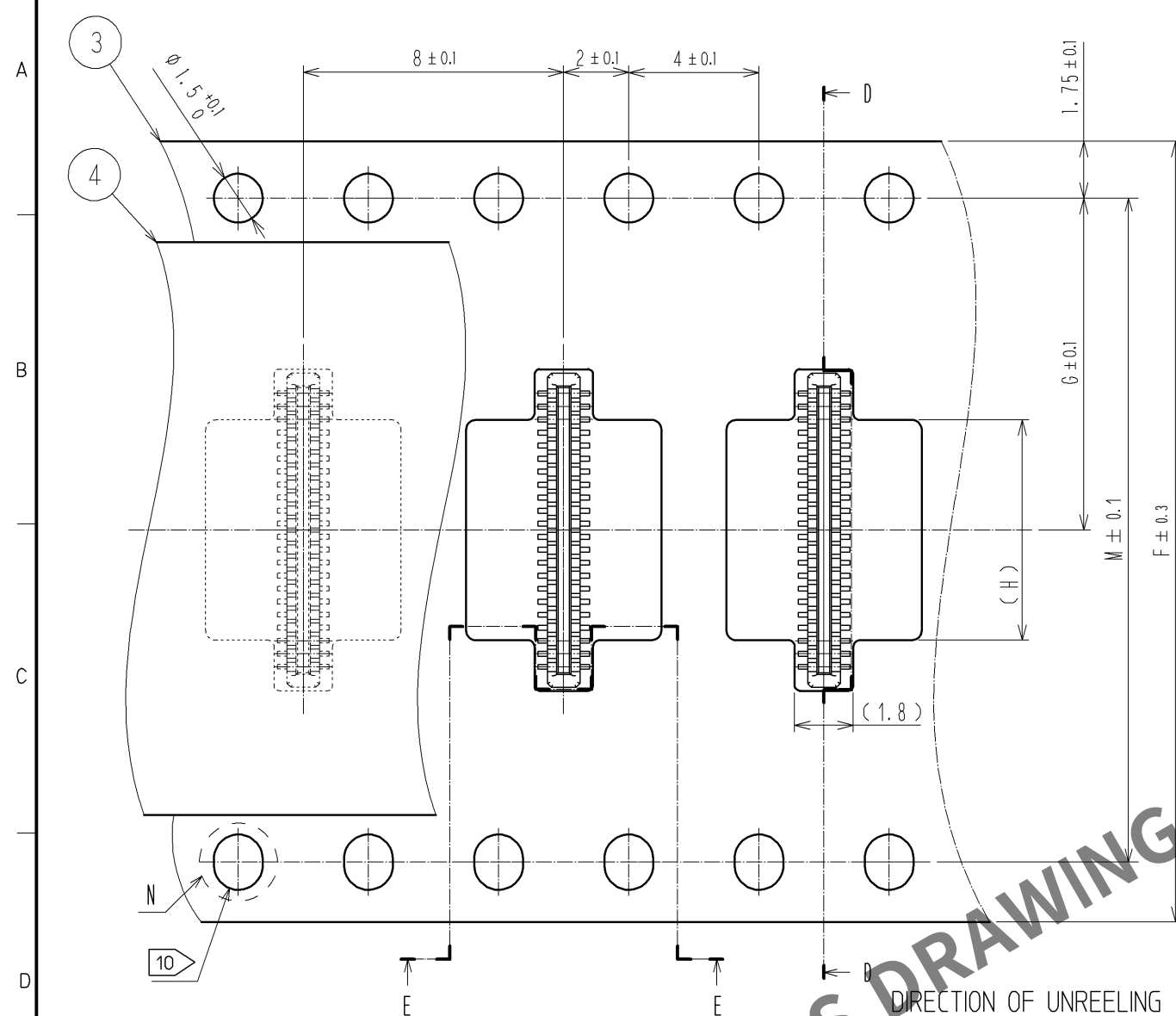
- REFLOW METHOD: IR REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
- 1) REFLOW TIME
DURATION ABOVE 220°C, 60 SEC. MAX.
(PEAK TEMPERATURE: 250°C MAX)
 - 2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90-120 sec.

6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE,
A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

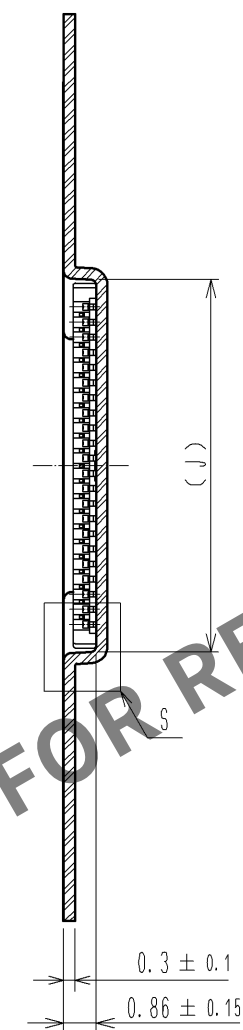
HRS

DRAWING NO.	EDC3-322328-04
PART NO.	BM14B(0.8)-*DP-0.4V(51)
CODE NO.	CL684

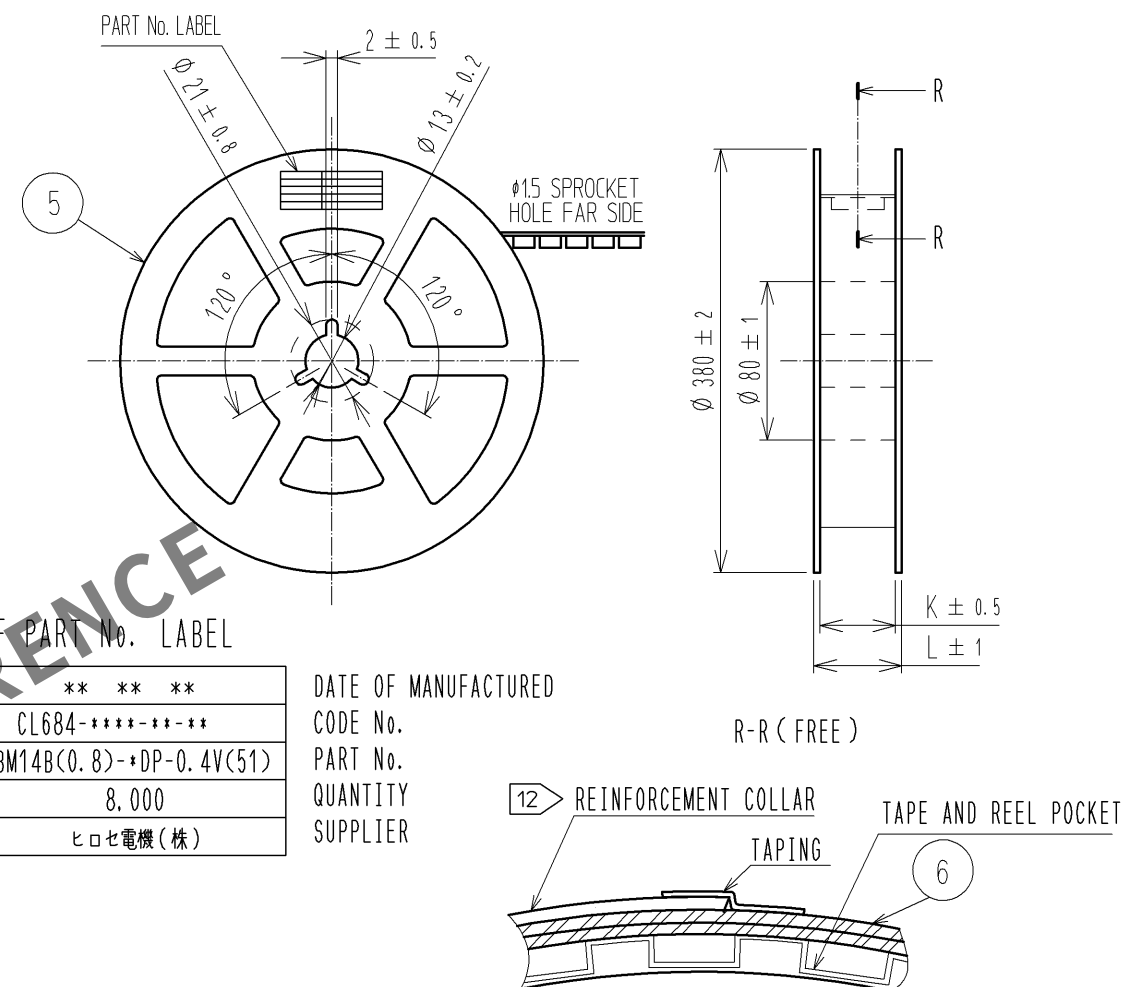
ENBOSSED CARRIER TAPE PACKAGING (5:1)



D-D (5:1)



STYLE AND DIMENTION OF REEL (FREE)



PART No.	F	G	H	J	K	L	M
BM14B(0.8)-10DP-0.4V(51)	12	5.5	—	3.88	13.5	17.5	—
BM14B(0.8)-12DP-0.4V(51)	12	5.5	—	4.28	13.5	17.5	—
BM14B(0.8)-20DP-0.4V(51)	16	7.5	2.77	5.88	17.5	21.5	—
BM14B(0.8)-22DP-0.4V(51)	16	7.5	3.17	6.28	17.5	21.5	—
BM14B(0.8)-24DP-0.4V(51)	16	7.5	3.57	6.68	17.5	21.5	—
BM14B(0.8)-30DP-0.4V(51)	24	11.5	4.77	7.88	25.5	29.5	—
BM14B(0.8)-34DP-0.4V(51)	24	11.5	5.57	8.68	25.5	29.5	—
BM14B(0.8)-40DP-0.4V(51)	24	11.5	6.77	9.88	25.5	29.5	—
BM14B(0.8)-50DP-0.4V(51)	24	11.5	8.77	11.88	25.5	29.5	—
BM14B(0.8)-60DP-0.4V(51)	24	11.5	10.77	13.88	25.5	29.5	—

7. PER REEL 8000 CONNECTORS.
8. THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.
9. REFER TO JIS C 0806(PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)
10. EMBOSSED CARRIER TAPE USED ON 10 TO 60 POSITIONS HAS THE SPROCKET HOLE ON ONE SIDE.
11. 10 POS AND 12POS POCKET SHAPE ARE AS SHOWN IN THE FIGURE.
12. AFTER PACKAGING, ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET, AND TAPE DOWN AT THE END THE COLLAR.

